

VUTL004R030NA

Datasheet

VMDSEMI



VUTL004R030NA

General Description

| V _{(BR)DSS} | R _{DS(ON)_max} | ID |
|----------------------|-------------------------|-------|
| 40V | 3.0mΩ@10V | 120 4 |
| | 4.4mΩ@4.5V | 130A |

Symbol

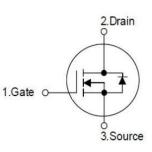


Figure 1 Symbol of VUTL004R030NA

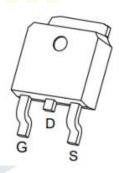
Features

- Trench Technology Power MOSFET
- Low R_{DS(ON)}
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Battery protection applications
- Power Switch Application

Package Type



TO-252-2LFigure 2Package Type of VUTL004R030NA

Ordering Information

| Product Name | Package |
|---------------|-----------|
| VUTL004R030NA | TO-252-2L |



VUTL004R030NA

Absolute Maximum Ratings (T_A= 25 °C, unless otherwise specified)

| Parameter | Symbol | Rating | Unit | |
|---|-----------------|------------|------|--|
| Drain-Source Voltage | V _{DS} | 40 | V | |
| Gate-Source Voltage | V _{GS} | ±20 | V | |
| Continuous Drain Current ^{Note1} $T_C = 25 \text{ °C}$ | ID | 130 | | |
| Pulsed Drain Current Note2 | I _{DM} | 350 | A | |
| Avalanche Current ^{Note3} | I _{AS} | 50 | A | |
| Single Pulsed Avalanche Energy ^{Note3} | E _{AS} | 625 | mJ | |
| Total Power Dissipation ^{Note5} $T_C= 25 \ ^{\circ}C$ | PD | 56 | W | |
| Junction Temperature | TJ | 150 | °C | |
| Storage Temperature | Tstg | -55 to 150 | °C | |

Thermal Resistance

| Parameter | Symbol | Min (| Т <mark>у</mark> р | Max | Unit |
|--------------------------------------|--------|-------|--------------------|-----|------|
| Thermal Resistance, Junction-to-Case | Røjc | | 2 <mark>.2</mark> | | °C/W |

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| Symbol | Test Conditions | Min | Тур | Max | Unit | |
|---------------------|--|--|--|--|--|--|
| | | | | | | |
| BV _{DSS} | $V_{GS}=0V, I_{D}=250uA$ | 40 | | | V | |
| I _{DSS} | $V_{DS}=32V, V_{GS}=0V$ | | | 1 | uA | |
| I _{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ±100 | nA | |
| V _{GS(th)} | V _{DS} =V _{GS} , I _D =250uA | 1.0 | 1.7 | 3.0 | V | |
| R _{DS(ON)} | $V_{GS}=10V, I_D=30A$ | | 2.3 | 3.0 | mΩ | |
| | V_{GS} =4.5V, I_D = 10A | | 2.9 | 4.4 | | |
| | | | | | | |
| CISS | V _{DS} =20V | | 9653 | | pF | |
| Coss | V _{GS} =0V | | 666 | | pF | |
| C _{RSS} | f=1MHz | | 660 | | pF | |
| Qg | V _{DS} =20V | | 30.1 | | | |
| Qgs | V _{GS} =10V | | 5.2 | | nC | |
| Q _{gd} | $I_D = 30A$ | | 9.8 | | | |
| Rg | f = 1MHz, Open drain | | 1.13 | | Ω | |
| | | | | | | |
| t _{d(on)} | V _{DD} = 15V | | 12.3 | | | |
| tr | $V_{GS}=10V$ | | 6.5 | | | |
| t _{d(off)} | I _D = 15A | | 48 | | – ns | |
| t _f | $R_{G}=3.3\Omega$ | | 9.2 | | | |
| | | | 1 | | | |
| V _{SD} | $V_{GS}=0V, I_{S}=10A$ | | | 1.2 | V | |
| | BV _{DSS} I _{DSS} I _{GSS} V _{GS(th)} R _{DS(ON)} C _{ISS} C _{OSS} C _{RSS} Q _g Q _g Q _g Q _g Rg t _{d(on)} t _r t _{d(off)} t _f | $\begin{array}{ c c c c c c c } \hline & V_{GS} = 0V, I_{D} = 250uA \\ \hline & I_{DSS} & V_{GS} = 32V, V_{GS} = 0V \\ \hline & I_{GSS} & V_{GS} = \pm 20V, V_{DS} = 0V \\ \hline & V_{GS(th)} & V_{DS} = V_{GS}, I_{D} = 250uA \\ \hline & V_{GS} = 10V, I_{D} = 30A \\ \hline & V_{GS} = 4.5V, I_{D} = 10A \\ \hline & C_{ISS} & V_{DS} = 20V \\ \hline & C_{RSS} & f = 1MHz \\ \hline & Q_{g} & V_{DS} = 20V \\ \hline & Q_{gs} & V_{GS} = 10V \\ \hline & Q_{gd} & I_{D} = 30A \\ \hline & Rg & f = 1MHz, Open drain \\ \hline & t_{d(off)} & I_{D} = 15A \\ \hline & t_{f} & R_{G} = 3.3\Omega \\ \hline \end{array}$ | $\begin{array}{ c c c c c c c c c c c c c c c c c c c$ | $\begin{array}{ c c c c c c c c c c c c c c c c c c c$ | $\begin{array}{ c c c c c c c c c c c c c c c c c c c$ | |

Electrical Characteristics (T_J= 25 °C, unless otherwise specified)

Notes :

1. The maximum current rating is limited by package. And device mounted on a large heatsink.

2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.

 $3.E_{AS}$ condition: $V_{DD} = 25V$, $V_{GS} = 10V$, L = 0.5mH, $R_G = 25\Omega$ Starting $T_J = 25^{\circ}C$.

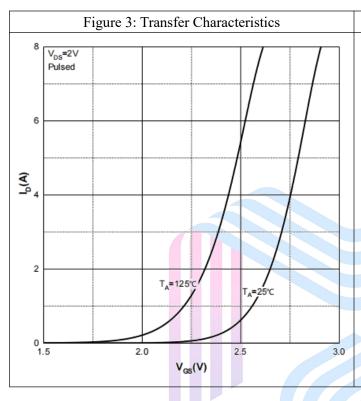
4.Pulse Test : Pulse Width \leq 300µs, duty cycle \leq 2%.

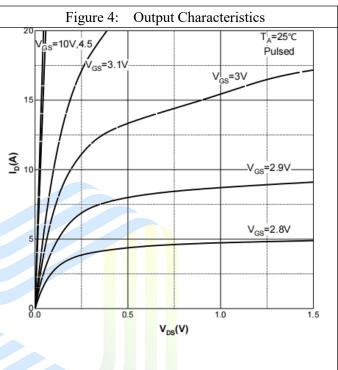
5. The power dissipation P_D is limited by $T_{J(MAX)} = 150^{\circ}$ C. And device mounted on a large heatsink

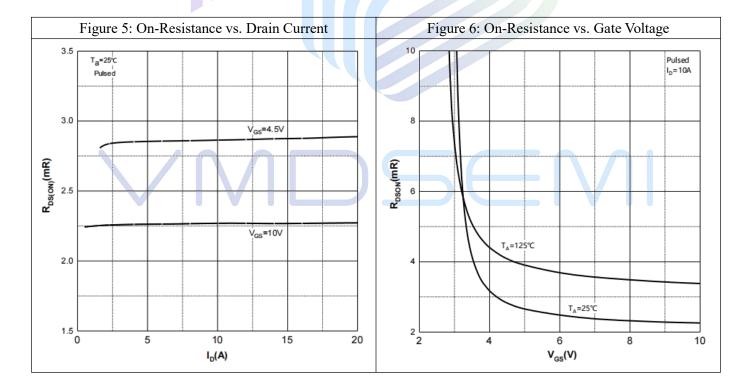


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Typical Performance Characteristics

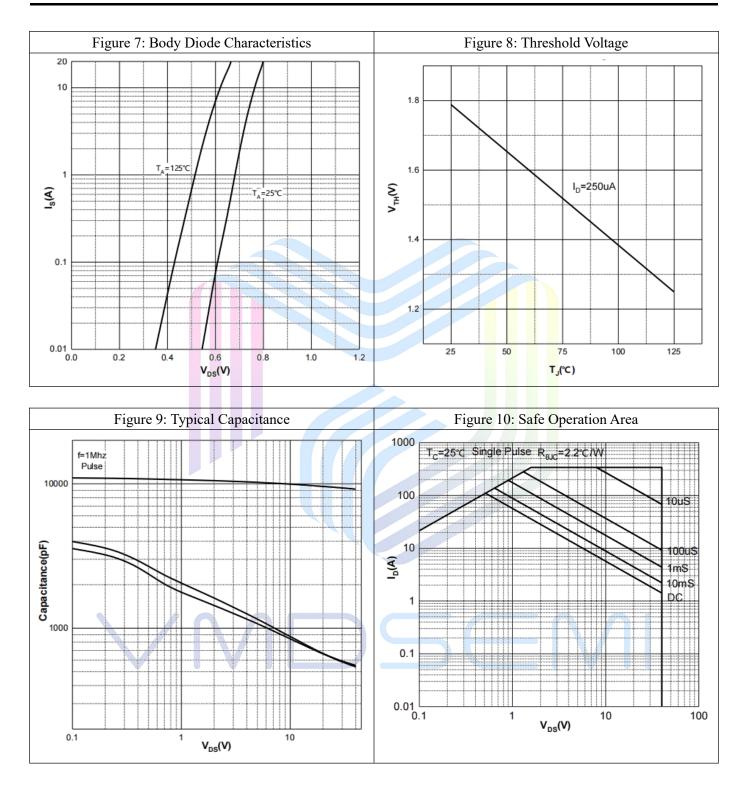






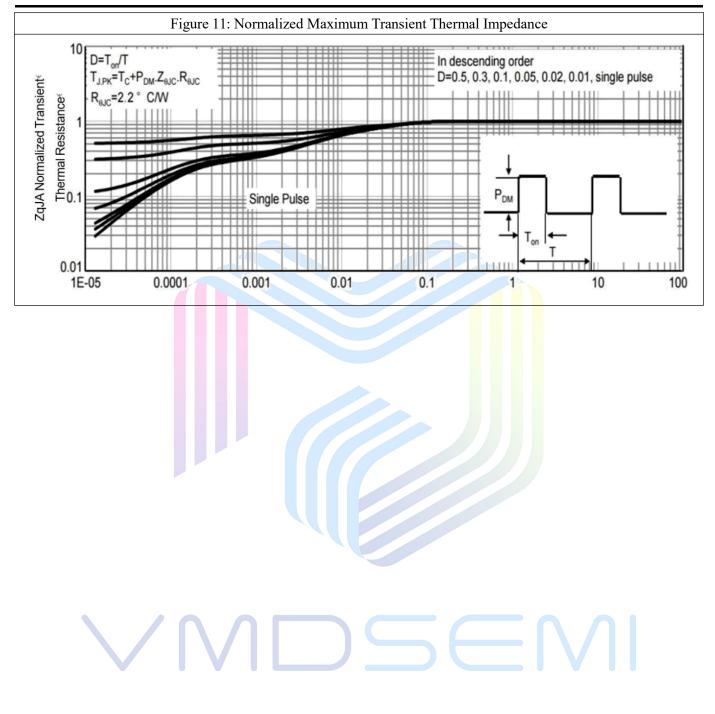


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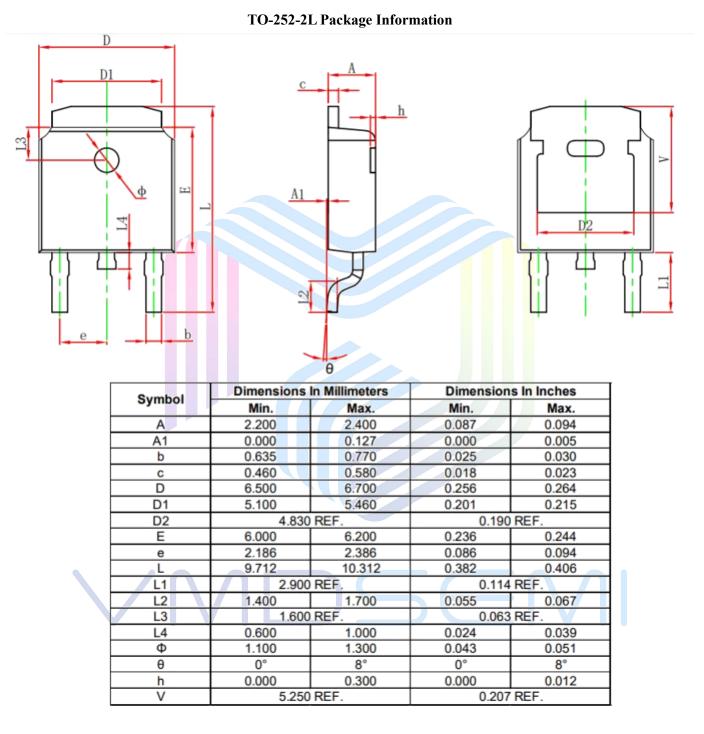
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Mechanical Dimensions:





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